



GENERAL FEATURES

V _{DS} (V)	Typical R _{DS(on)} (mΩ)
-30	11@ V _{GS} =-10V
	15 @ V _{GS} =-5V

Package and Pin Configuration

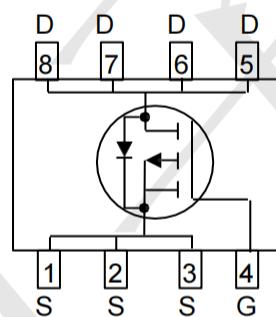


SOP-8 top view

Application

- Load/Power Switching
- Interfacing Switching
- Logic Level Shift

Circuit diagram



Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

Parameter	Symbol	Maximum	Unit
Drain-Source Voltage	V _{DS}	-30	V
Gate-Source Voltage	V _{GS}	±25	
Continuous Drain Current	I _D	-13	A
		-10	
Pulsed Drain Current ^c	I _{DM}	-72	
Maximum Power Dissipation ^b	P _D	3.8	W
		2.4	
Operating Junction Temperature	T _J	-55 to 150	°C
Storage Temperature Range	T _{STG}	-55 to 150	°C

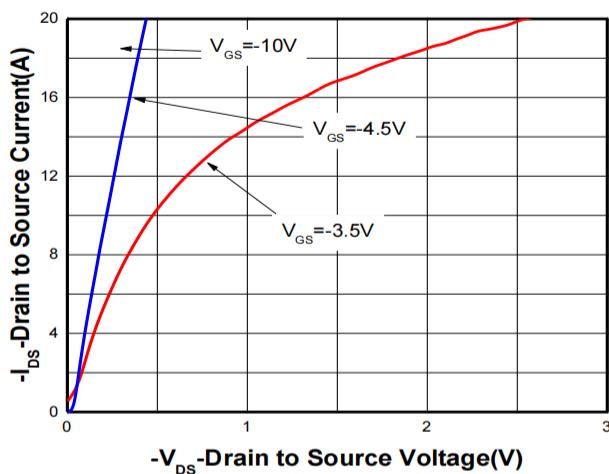
Thermal resistance ratings

Single Operation					
Parameter	Symbol	Typical	Maximum	Unit	
Junction-to-Ambient Thermal Resistance ^a	t ≤ 10 s	R _{θJA}	25	33	°C/W
	Steady State		50	63	
Junction-to-Lead Thermal Resistance	Steady State	R _{θJL}	10	13	

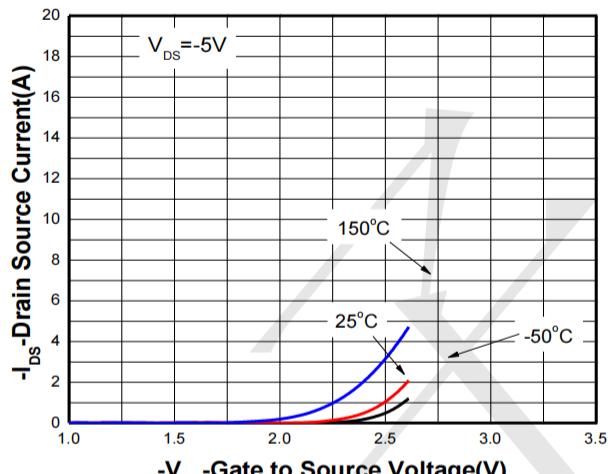
Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage	BV_{DSS}	$\text{V}_{\text{GS}} = 0 \text{ V}, \text{I}_D = -250\mu\text{A}$	-30			V
Zero Gate Voltage Drain Current	I_{DSS}	$\text{V}_{\text{DS}} = -24\text{V}, \text{V}_{\text{GS}} = 0\text{V}$			-1	μA
Gate-to-source Leakage Current	I_{GSS}	$\text{V}_{\text{DS}} = 0 \text{ V}, \text{V}_{\text{GS}} = \pm 25\text{V}$			± 100	nA
ON CHARACTERISTICS						
Gate Threshold Voltage	$\text{V}_{\text{GS(TH)}}$	$\text{V}_{\text{GS}} = \text{V}_{\text{DS}}, \text{I}_D = -250\mu\text{A}$	-1.0	-1.8	-3.0	V
Drain-to-source On-resistance	$\text{R}_{\text{DS(on)}}$	$\text{V}_{\text{GS}} = -10\text{V}, \text{I}_D = -13\text{A}$		11	15	$\text{m}\Omega$
		$\text{V}_{\text{GS}} = -5\text{V}, \text{I}_D = -7\text{A}$		15	20	
Forward Transconductance	g_{FS}	$\text{V}_{\text{DS}} = -5 \text{ V}, \text{I}_D = -8\text{A}$		7	16	S
CHARGES, CAPACITANCES AND GATE RESISTANCE						
Input Capacitance	C_{iss}	$\text{V}_{\text{GS}} = 0 \text{ V}, f = 1.0\text{MHz}, \text{V}_{\text{DS}} = -15 \text{ V}$		2106		pF
Output Capacitance	C_{oss}			353		
Reverse Transfer Capacitance	C_{rss}			274		
Total Gate Charge	$\text{Q}_{\text{G(TOT)}}$	$\text{V}_{\text{GS}} = -10 \text{ V}, \text{V}_{\text{DS}} = -15 \text{ V}, \text{I}_D = -13 \text{ A}$		38		nC
Threshold Gate Charge	$\text{Q}_{\text{G(TH)}}$			4		
Gate-to-Source Charge	Q_{GS}			7.7		
Gate-to-Drain Charge	Q_{GD}			6.5		
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	td(ON)	$\text{V}_{\text{GS}} = -10 \text{ V}, \text{V}_{\text{DS}} = -15 \text{ V}, \text{I}_D = -5\text{A}, \text{R}_G = 6\Omega$		18		ns
Rise Time	tr			24		
Turn-Off Delay Time	td(OFF)			114		
Fall Time	tf			47		
BODY DIODE CHARACTERISTICS						
Forward Voltage	V_{SD}	$\text{V}_{\text{GS}} = 0 \text{ V}, \text{I}_S = -1\text{A}$	-0.5	-0.8	-1.2	V

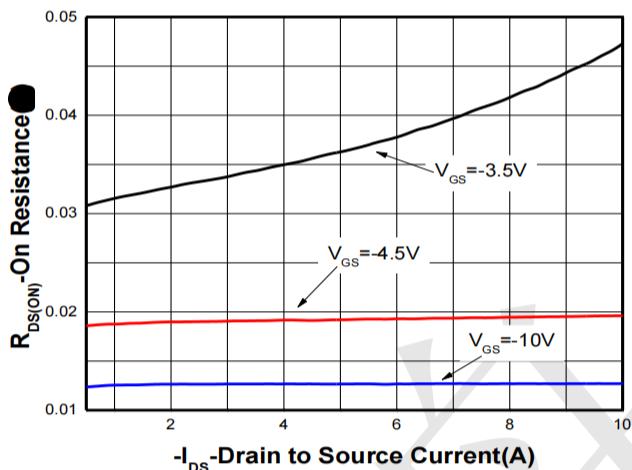
Typical Electrical and Thermal Characteristics



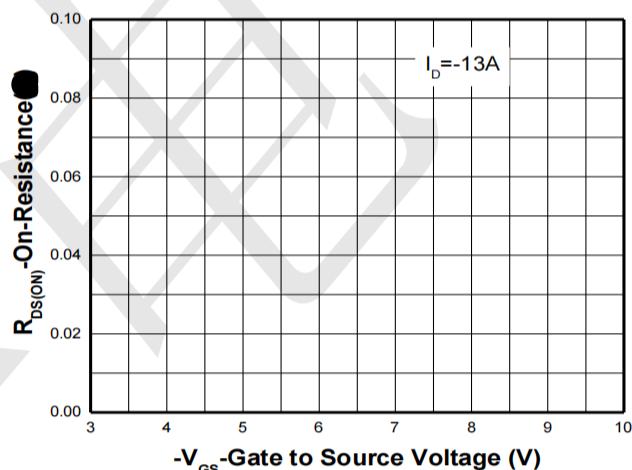
Output characteristics



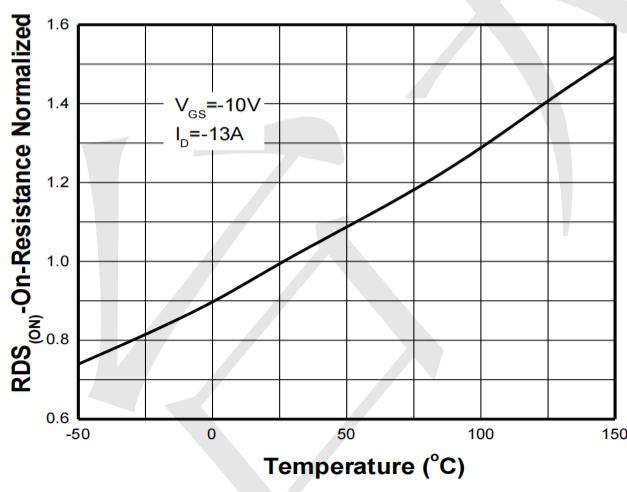
Transfer characteristics



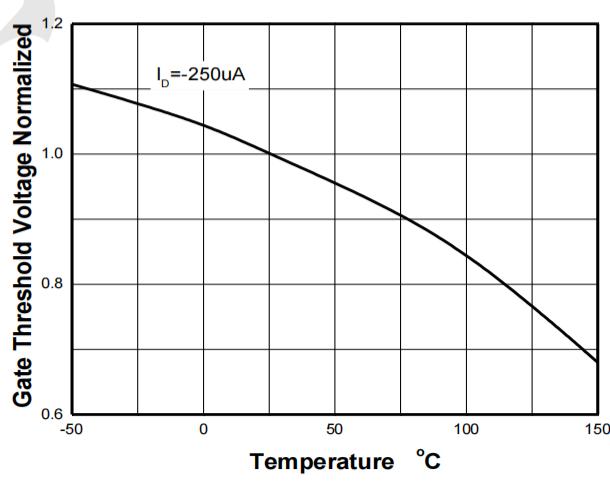
On-Resistance vs. Drain current



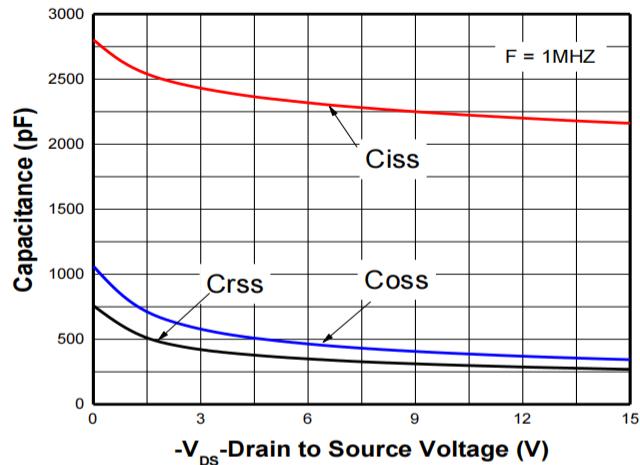
On-Resistance vs. Gate-to-source voltage



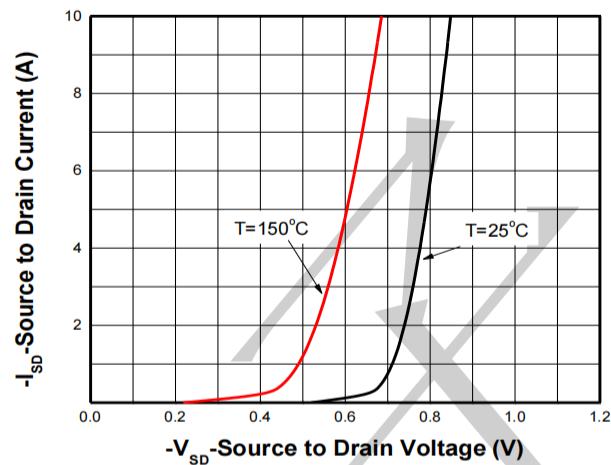
On-Resistance vs. Junction temperature



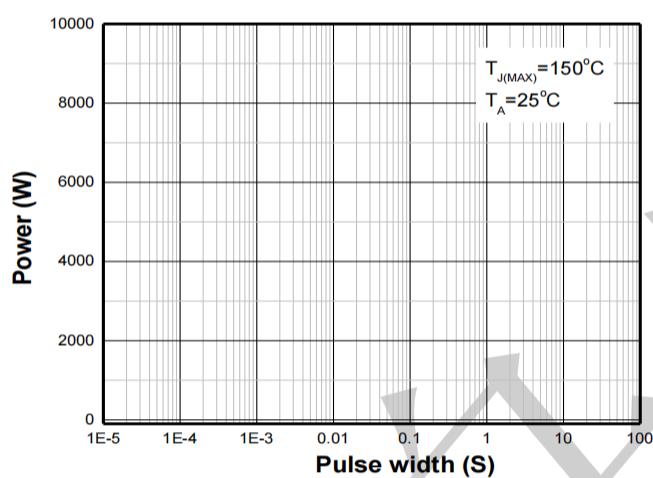
Threshold voltage vs. Temperature



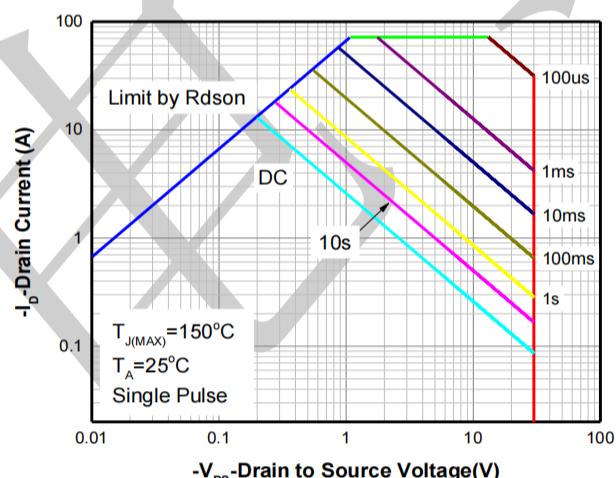
Capacitance



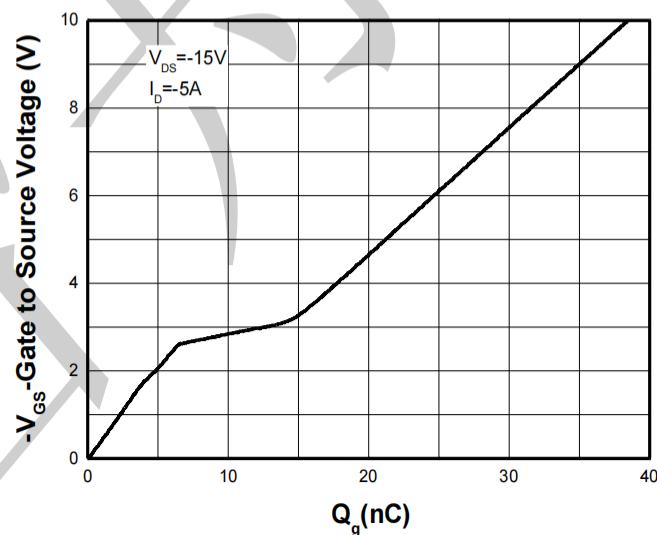
Body diode forward voltage



Single pulse power



Safe operating power



Gate Charge Characteristics



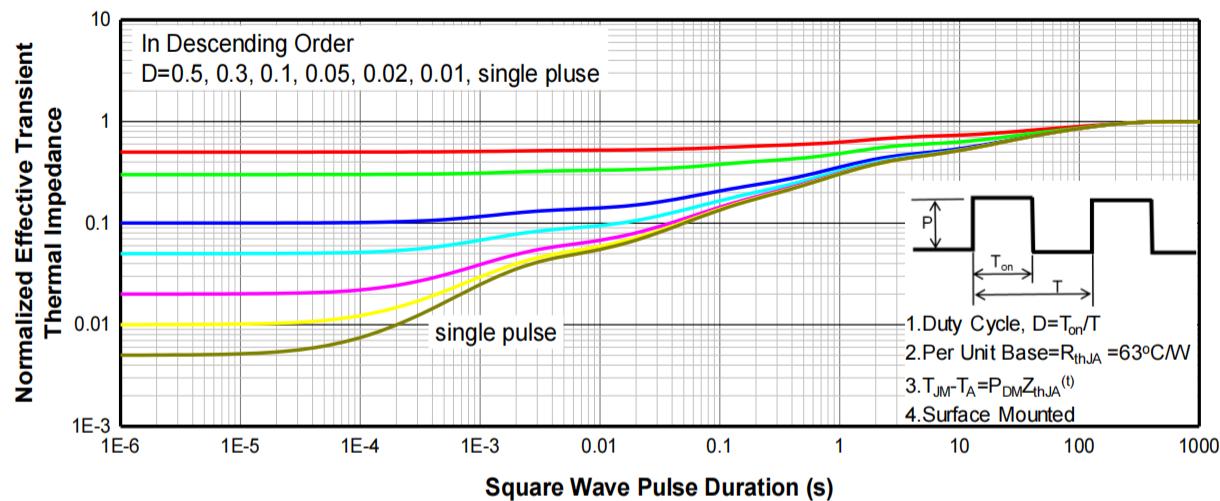
TECH PUBLIC
台舟电子

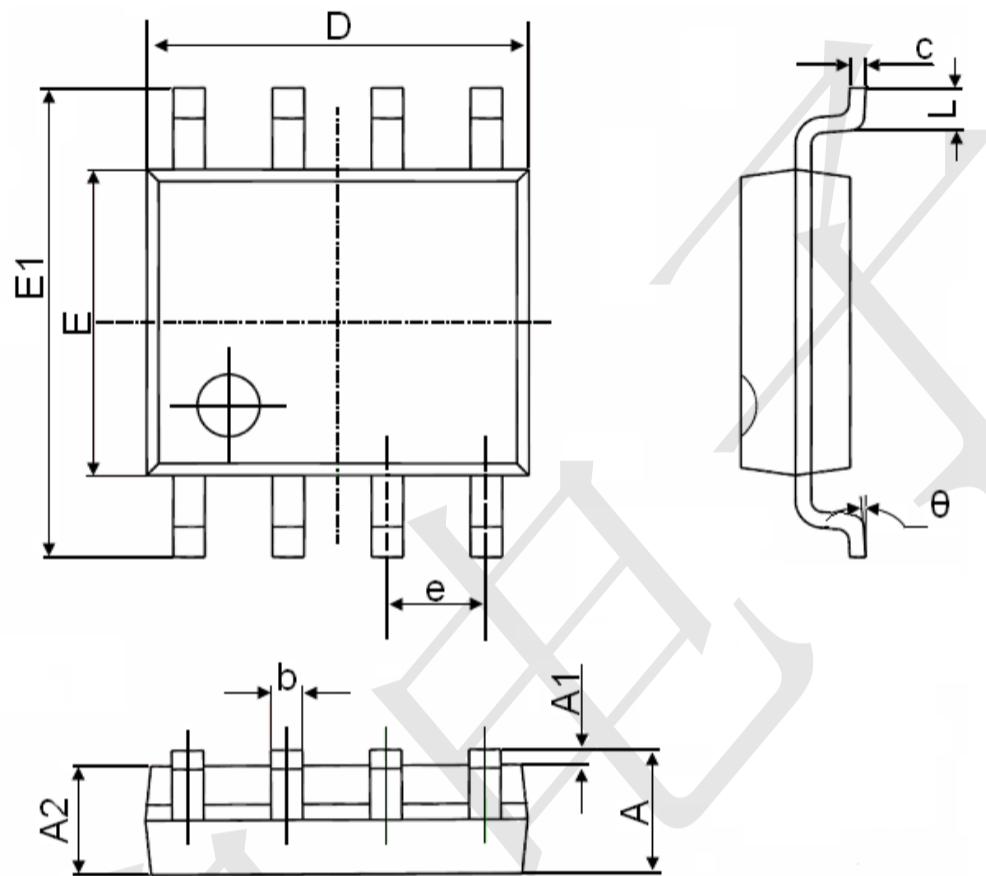
IRF9388TRPBF-TP

P-Channel Enhancement Mode Power MOSFET

WWW.TECHPUBLIC.COM

Transient Thermal Response (Junction-to-Ambient)



SOP-8 Package Information

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°